

Z-PACK | Z-PACK 2mm HM

TE Internal #: 5646446-1

Hard Metric Backplane Connectors, PCB Mount Receptacle, ≤1 Gb

/s, 11 Column, 8 Row, Mezzanine, 88 Position, 2 mm [.078 in]

Centerline, Z-PACK 2mm HM

View on TE.com >



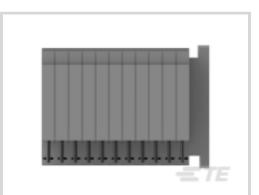
Connectors > PCB Connectors > Backplane Connectors > Hard Metric Backplane Connectors >

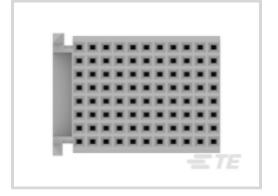
HM Receptacle Connector: Traditional Backplane, Coplanar, 2mm











PCB Connector Assembly Type: PCB Mount Receptacle

Data Rate: ≤1 Gb/s

Number of Columns: 11

Number of Rows: 8

Backplane Architecture: Mezzanine

All HM Receptacle Connector: Traditional Backplane, Coplanar, 2mm (48)

Features

Product Type Features

Backplane Interface Type	2mm HM
Connector System	Board-to-Board
Connector & Contact Terminates To	Printed Circuit Board
PCB Connector Assembly Type	PCB Mount Receptacle
Sealable	No

Configuration Features

Rows Loaded	A, B, C, D, E, F, G, H
Number of Signal Positions	88
Number of Columns	11
Number of Rows	8
Backplane Architecture	Mezzanine
Number of Positions	88



Signal Characteristics Crosstalk Version Standard Data Rate <1 Gb/s Body Features Primary Product Color Gray Contact Features Feedthrough Post Length 3.3 mm CompactPCI Designation None Contact Type Socket Contact Type Socket Contact Termination Area Plating Material Nickel PCB Contact Termination Area Plating Material Phosphor Bronze Contact Mating Area Plating Material Performance Based Contact Mating Area Plating Material Performance Based Contact Mating Area Plating Material Thickness 7.6 um/30 µin Contact Current Rating (Max) 1.5 A Termination Features Termination Features Termination Method to Printed Circuit Board Through Hole - Press-Fit Mechanical Attachment Mating Alignment Type Multi-Purpose Center Connector Mounting Type Board Mount Housing Features Housing Material Polyester - GF Centerline (Pitch) 2 mm(1078 in 1) Dimensions Backclaine Module Length 25 mm Usage Conditions Operation/Application Sheided No Circuit Application Signal	PCB Mount Orientation	Right Angle
Cosstalk Version Standard at Gb/s Body Features Primary Product Color Gray Contact Features Footest Longth 3.3 mm Compact PCI Designation None Contact Type Socket Contact Underplating Material Nickel PCB Contact Termination Area Plating Material Tin Contact Base Material Phosphor Bronze Contact Mating Area Plating Material Performance Based Contact Mating Area Plating Material Performance Based Contact Mating Area Plating Material Thickness J/6 µm(30 µin) Contact Current Rating (Max) 1.5 A Termination Features Termination Method to Printed Circuit Board Through Hole - Press-Fit Mechanical Attachment Methanical Attachment Methanical Attachment Footened or Mounting Type Board Mount Housing Features Housing Material Polyester - Gif Centedine (Pitch) 2 mm(1.078 in) Dimensions Backplane Module Length 25 mm Usage Conditions Operating Temperature Range 55 125 °C[67 - 257 °F] Operating Temperature Range No		rught/ uigic
Data Rate ≤1 Gb/s Body Features Primary Product Color Gray Contact Features Feedthrough Post Length 3.3 mm CompactPCI Designation None Contact Type Socket Contact Underplating Material Nickel PCB Contact Termination Area Plating Material Tin Contact Base Material Phosphor Bronze Contact Mating Area Plating Material Performance Based Contact Mating Area Plating Material Performance Based Contact Mating Area Plating Material Thickness 7.6 μm/30 μin/ Contact Current Rating (Max) 1.5 Λ Termination Features Termination Method to Printed Circuit Board Through Hole - Press-Fit Mechanical Attachment Meting Alignment Type Multi-Purpose Center Connector Mounting Type Board Mount Housing Features Housing Material Palyester GF Centedine (Pitch) 2 mm/,078 in/ Dimensions Backplane Module Length 25 mm Usage Conditions Operating Temperature Range -55 - 125 °C -67 - 257 °T Operation/Application Shielded No		
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Primary Product Color Contact Features Feedthrough Post Length 3.3 mm CompactPCI Designation None Contact Type Socket Contact Underplating Material Nickel PCB Contact Termination Area Plating Material Tin Contact Base Material Phrosphor Bronze Contact Mating Area Plating Material Performance Based Contact Mating Area Plating Material Performance Based Contact Mating Area Plating Material Thickness 7.6 µm [30 µm] Contact Current Rating (Max) 1.5 A Termination Features Termination Method to Printed Circuit Board Through Hole - Press-Fit Mechanical Attachment Mating Alignment Type Multi Purpose Center Connector Mounting Type Board Mount Housing Features Housing Material Polyester - GF Centerline (Pitch) 2 mm [0.78 in] Dimensions Backplarie Module Length 25 mm Usage Conditions Operation/Application Shielded No		≤1 Gb/s
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CompactPCI Designation None Contact Type Socket Contact Underplating Material Nickel PCB Contact Termination Area Plating Material Tin Contact Base Material Phosphor Bronze Contact Mating Area Plating Material Performance Based Contact Mating Area Plating Material Thickness .76 µm(30 µin) Contact Current Rating (Max) 1.5 A Termination Features Termination Method to Printed Circuit Board Through Hole - Press-Fit Mechanical Attachment Mating Alignment Type Multi-Purpose Center Connector Mounting Type Board Mount Housing Features Housing Material Polyester GF Centerline (Pitch) 2 mm(.078 in) Dimensions Backplane Module Length 25 mm Usage Conditions Operation/Application Shielded No	Contact Features	
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Contact Current Rating (Max) Termination Features Termination Method to Printed Circuit Board Mechanical Attachment Mating Alignment Type Connector Mounting Type Board Mount Housing Features Housing Material Polyester - GF Centerline (Pitch) 2 mm[.078 in] Dimensions Backplane Module Length 25 mm Usage Conditions Operating Temperature Range -55 - 125 °C[-67 - 257 °F] Operation/Application Shielded No	Contact Mating Area Plating Material	Performance Based
Termination Features Termination Method to Printed Circuit Board Through Hole - Press-Fit Mechanical Attachment Mating Alignment Type Multi-Purpose Center Connector Mounting Type Board Mount Housing Features Housing Material Polyester - GF Centerline (Pitch) 2 mm[.078 in] Dimensions Backplane Module Length 25 mm Usage Conditions Operating Temperature Range -55 - 125 °C[-67 - 257 °F] Operation/Application Shielded No	Contact Mating Area Plating Material Thickness	.76 μm[30 μin]
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Mechanical AttachmentMating Alignment TypeMulti-Purpose CenterConnector Mounting TypeBoard MountHousing FeaturesHousing MaterialCenterline (Pitch)2 mm[.078 in]Dimensions25 mmBackplane Module Length25 mmUsage Conditions-55 - 125 °C[-67 - 257 °F]Operation/ApplicationNo	Termination Features	
Mating Alignment Type Connector Mounting Type Board Mount Housing Features Housing Material Polyester - GF Centerline (Pitch) 2 mm[.078 in] Dimensions Backplane Module Length 25 mm Usage Conditions Operating Temperature Range -55 - 125 °C[-67 - 257 °F] Operation/Application Shielded No	Termination Method to Printed Circuit Board	Through Hole - Press-Fit
Connector Mounting Type Housing Features Housing Material Polyester - GF Centerline (Pitch) 2 mm[.078 in] Dimensions Backplane Module Length 25 mm Usage Conditions Operating Temperature Range -55 - 125 °C[-67 - 257 °F] Operation/Application Shielded No	Mechanical Attachment	
Housing Features Housing Material Polyester - GF Centerline (Pitch) 2 mm[.078 in] Dimensions Backplane Module Length 25 mm Usage Conditions Operating Temperature Range -55 - 125 °C[-67 - 257 °F] Operation/Application Shielded No	Mating Alignment Type	Multi-Purpose Center
Housing Material Polyester - GF Centerline (Pitch) 2 mm[.078 in] Dimensions Backplane Module Length 25 mm Usage Conditions Operating Temperature Range -55 - 125 °C[-67 - 257 °F] Operation/Application Shielded No	Connector Mounting Type	Board Mount
Centerline (Pitch) Dimensions Backplane Module Length Usage Conditions Operating Temperature Range Operation/Application Shielded No	Housing Features	
Dimensions Backplane Module Length 25 mm Usage Conditions Operating Temperature Range -55 - 125 °C[-67 - 257 °F] Operation/Application Shielded No	Housing Material	Polyester - GF
Backplane Module Length 25 mm Usage Conditions Operating Temperature Range -55 - 125 °C[-67 - 257 °F] Operation/Application Shielded No	Centerline (Pitch)	2 mm[.078 in]
Usage Conditions Operating Temperature Range -55 - 125 °C[-67 - 257 °F] Operation/Application Shielded No	Dimensions	
Operating Temperature Range -55 - 125 °C[-67 - 257 °F] Operation/Application Shielded No	Backplane Module Length	25 mm
Operation/Application Shielded No	Usage Conditions	
Shielded	Operating Temperature Range	-55 - 125 °C[-67 - 257 °F]
	Operation/Application	
Circuit Application Signal	Shielded	No
	Circuit Application	Signal



Industry Standards

UL Flammability Rating	UL 94V-0
Packaging Features	
Packaging Quantity	20
Packaging Method	Box

Product Compliance

For compliance documentation, visit the product page on TE.com>

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JAN 2024 (240) Candidate List Declared Against: JAN 2024 (240) Does not contain REACH SVHC
Halogen Content	Not Low Halogen - contains Br or Cl > 900 ppm.
Solder Process Capability	Not applicable for solder process capability

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

Compatible Parts





TE Part # CAT-472-Z12 Hard Metric Male Connector: Traditional Backplane, Mezzanine, 2mm

TE Part # 2170310-2 2MM HM,ASY,T-F,PIN,088 POS TE Part # 3-5646457-0 2MM HM,ASY,T-F,PIN,088 POS

Also in the Series | Z-PACK 2mm HM



Backplane Connector Housings(4)



Backplane Power Connectors(6)



Connector Caps & Covers(62)



Connector Contacts(2)



Connector Hardware(97)



Hard Metric Backplane Connectors



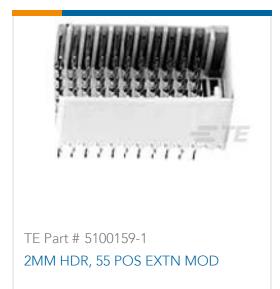
High Speed Backplane Connectors(1)



Insertion & Extraction Tools(2)



Customers Also Bought





TE Part # 3-2343522-3 SFP56 Stacked Cage Assembly: EMI Spring













TE Part # 3-2340033-5 SFP56 STACKED 2X8 RECEPTACLE ASSEMBLY



Documents

Product Drawings

2MM HM,ASY,T-F,REC,TWIST TULIP

English

CAD Files

3D PDF

English

Customer View Model

ENG_CVM_5646446-1_A.2d_dxf.zip

English

Customer View Model

ENG_CVM_5646446-1_A.3d_igs.zip

English

Customer View Model

ENG_CVM_5646446-1_A.3d_stp.zip

English

By downloading the CAD file I accept and agree to the **Terms and Conditions**of use.

Product Specifications

Application Specification

English